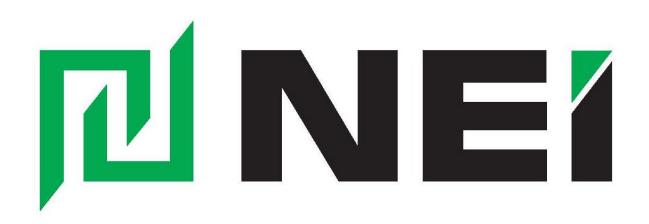
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	McKinney		
Assemblies Covered:			
E-2900 R2 (786-015	6-0X, 786-0157-0X, 78	86-0158-0X, 78	6-0159-0X)



Revision	Date	ECO#	Revised By	Description of Changes
0A			S.McKinney	Initial Release

Tools Required:

- #2 Phillips Screwdriver
- #1 Phillips Screwdriver
- Needle nose Pliers

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E-2900 R2 (786-0156-0X, 786-0157-0X, 786-0158-0X, 786-0159-0X)				

NOTE: Disconnect any AC Power Cords attached to the power supplies before disassembly of the unit.

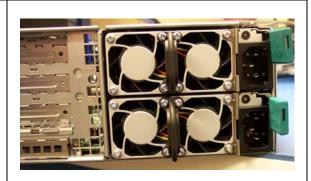
Removal of the top access cover requires a #2 Philips screwdriver. a. Remove the cover screw. b. Press the release button and ACCESS slide the top cover towards the COVER rear of the chassis about an inch. c. Remove access cover by lifting it d. Remove any labels from the chassis and access cover. e. Discard Sheet Metal Cover, **Cover Screw, and Labels in the** appropriate Recycling Bin. 1. RELEASE COVER BUTTON **SCREW** 2. Removal of the bezel brackets (if present) requires a #2 screwdriver. a. Remove the two (2) screws securing each bezel bracket to the chassis, and pull off the chassis. b. Discard Bezel Brackets and screws in the appropriate Recycling Bin.

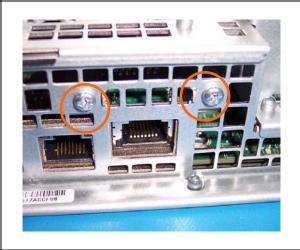
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Removal of the Power Supply (ies) does
not require any tools.
 a. Press and hold the green button

- towards the power supply handle.
 b. Pull the supply straight out of the
- rear of the chassis.

 c. Discard the Power Supply (ies) in the appropriate Recycling
- in the appropriate Recycling Bin.
- 4. Removal of the Remote Management Module (if present) requires a #2 Phillips screwdriver.
 - a. Remove the two (2) screws securing the module to the rear of the chassis.
 - b. Disconnect the module cable from the motherboard, and lift the module out of the chassis.





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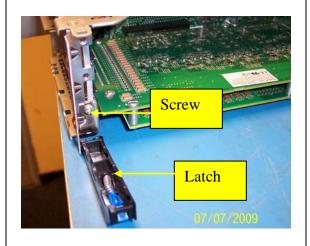
- 4. c. Remove the cable connected to the module.
 - d. Remove the three (3) screws securing the module bracket to the module.
 - e. Discard the Remote
 Management Module, cable,
 bracket, and screws in the
 appropriate Recycling Bin.



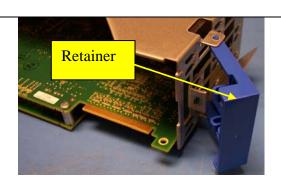
- 5. Removal of the PCI card assembly does not require any tools.
 - a. Remove the PCI card by holding the assembly on either end of the two blue marks and lifting it straight out of the chassis.



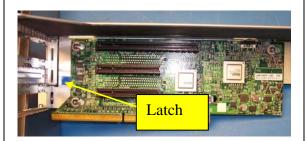
- 6. Removal of the PCI card (if installed) requires a #2 Phillips screw driver.
 - a. Remove the PCI card from the riser by pushing the blue lever on the latch and swinging the latch open, removing the screw securing the card to the bracket, flipping the rear card retainer open, and pulling the PCI card out away from the riser.
 - b. Discard the PCI card and screw in the appropriate Recycling Bin.



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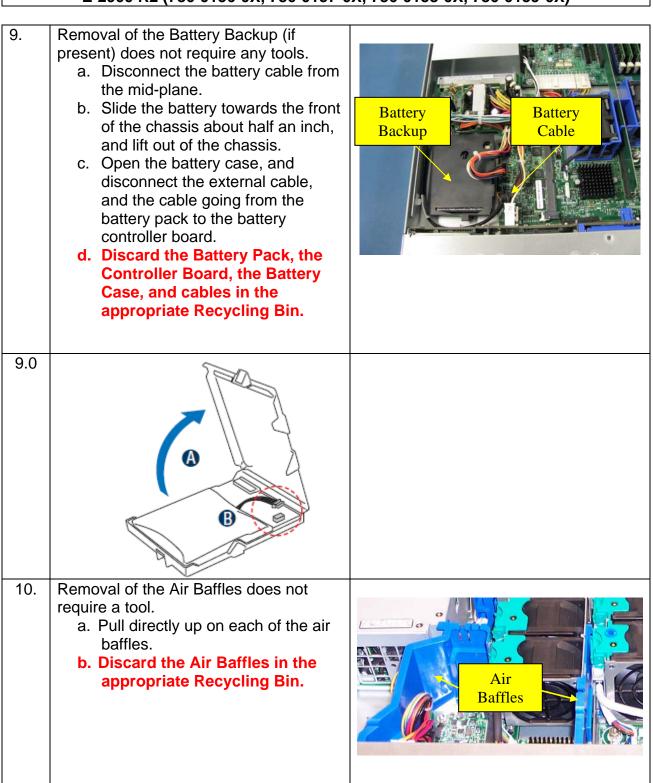
- 7. Removal of the PCI riser card does not require a tool.
 - a. Remove the PCI riser card from the bracket by pushing down on the blue bracket latch and sliding the riser card sideways towards the latch and then pulling straight up off the bracket.
 - b. Discard the PCI riser card and bracket in the appropriate Recycling Bin.



- 8. Removal of the Air Duct does not require any tools.
 - a. Remove the Air Duct by lifting it straight up and out of the chassis.
 - b. Discard the Air Duct in the appropriate Recycling Bin.

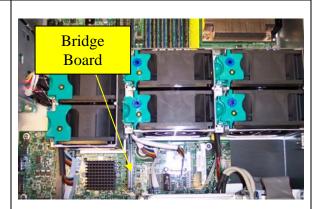


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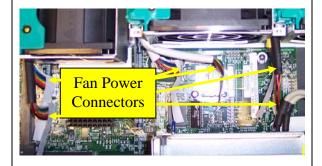
- 11. Removal of the Bridge Board does not require any tools.
 - a. Open the retention clips of the Bridge Board on the mid-plane, and motherboard.
 - b. Pull the Bridge Board straight up to remove.
 - c. Discard the Bridge Board in the appropriate Recycling Bin.



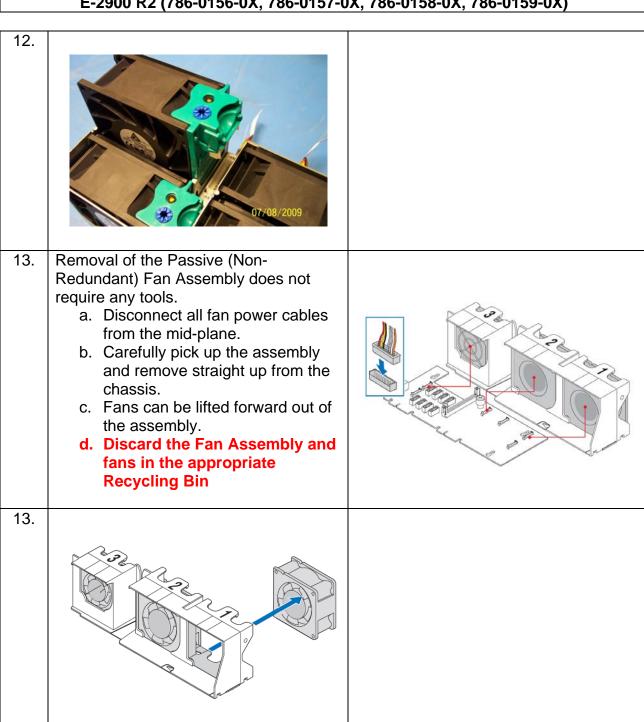




- 12. Removal of the Active (Redundant) Fan Assembly does not require any tools.
 - a. Disconnect all fan power cables from the mid-plane.
 - b. Carefully pick up the assembly and remove straight up from the chassis.
 - c. Fans can be lifted straight out of the assembly.
 - d. Discard the Fan Assembly and fans in the appropriate Recycling Bin



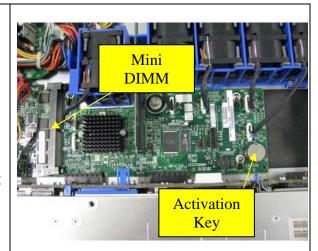
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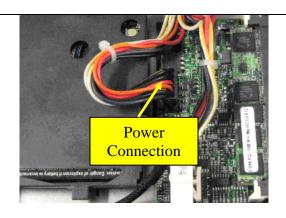
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14. Removal of the RAID Mini DIMM and RAID Activation Key does not require any tools.

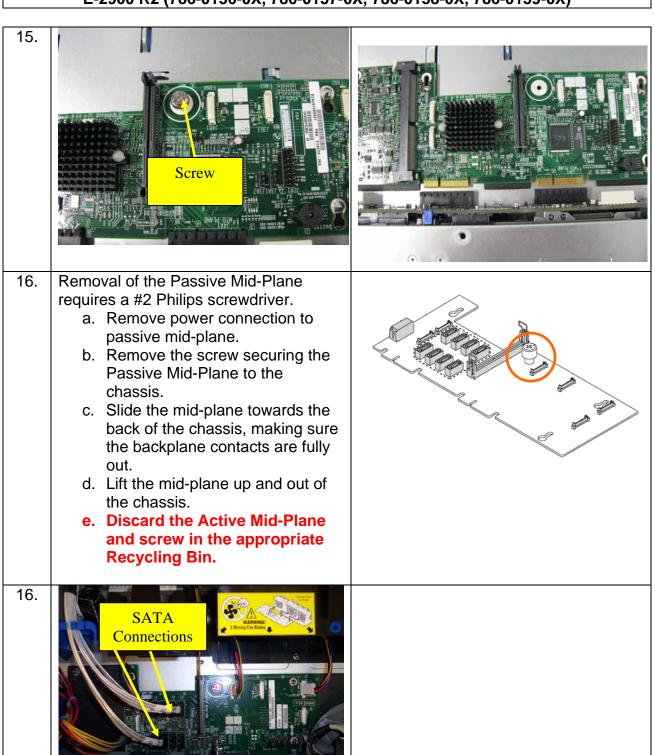
- Push the retaining clips on the RAID Mini DIMM away from the DIMM.
- b. Pull the DIMM away from the connector to remove.
- c. Push the tabs to the sides of the Activation Key and lift the key out of its connector.
- d. Discard the RAID Mini DIMM and RAID Activation Key in the appropriate Recycling Bin.



- Removal of the Active Mid-Plane requires a #2 Philips screwdriver.
 - a. Removal of power connection to active mid-plane.
 - b. Remove the screw securing the Active Mid-Plane to the chassis.
 - Slide the mid-plane towards the back of the chassis, making sure the backplane contacts are fully out.
 - d. Life the mid-plane up and out of the chassis.
 - e. Discard the Active Mid-Plane and screw in the appropriate Recycling Bin.

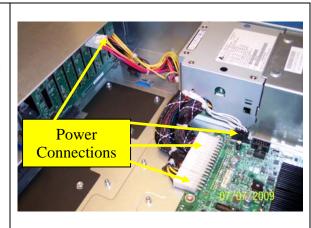


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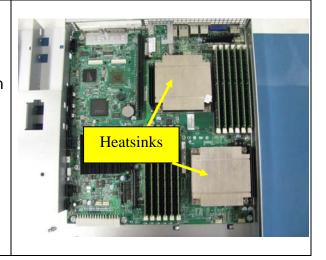
- 17. All remaining cable connectors need to be disconnected.
 - Disconnect all power cables from the surrounding powers (three on the motherboard and one on the backplane).
 - b. For passive system, remove all SATA cables from motherboard.
 - c. For 3.5" system with 6th HDD option, remove power and data cable from 6th HDD option card and backplane.
 - d. Discard all cables in the appropriate Recycling Bin.



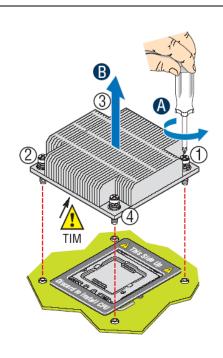




- 18. Removal of the CPU Heatsink(s) requires a #2 Philips screwdriver.
 - a. Start loosening the four (4) screws of each heatsink two turns at a time in the order shown in the picture below.
 - b. Once all screws are fully out, life the heatsinks out of the chassis.
 - c. Discard the Heatsink(s) in the appropriate Recycling Bin.



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- 19. Removal of the CPU(s) does not require any tools.
 - a. Push the latch down and then away from the CPU socket.
 - b. Open the load plate, and carefully remove the CPU from its socket.
 - c. Discard the CPU(s) in the appropriate Recycling Bin.



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- 20. Removal of the Memory DIMMs and Lithium Battery from the motherboard do not require any tools.
 - a. Remove each of the Memory DIMMs by pushing down and out on the two latches, one on each end of the DIMM connector. Lift memory DIMM straight out to remove.
 - b. Remove the coin style Lithium Battery.
 - c. Discard the Memory DIMMs and Lithium Battery in the appropriate Recycling Bin.

 *** CAUTION ***

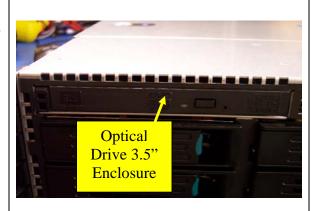
Care should be observed when disposing of the battery to avoid shorting it!

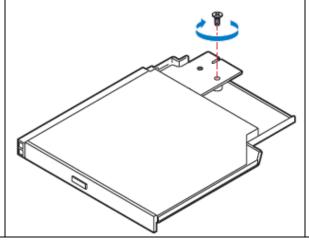




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- 22. Removal of the Optical Drive (if present) requires a #2 Philips screwdriver.
 - a. Press the tab on the plastic guide behind the backplane, and pull the drive straight out of the chassis.
 - b. For 2.5" drive enclosure, remove the two (2) screws securing the blue tab to the rear of the drive.
 - c. In case of 3.5" drive enclosure, the optical drive as an interposer board that must be removed from a CDROM carrier using a #2 Philips screwdriver.
 - d. Discard the Optical Drive,
 Plastic guide, Drive Carrier,
 Interposer Board, and screws
 in the appropriate Recycling
 Bin.

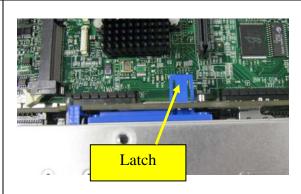






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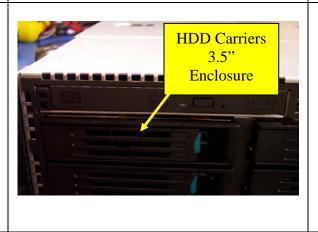






- 23. Removal of the 2.5" or 3.5" Hard Drive (s) requires a #2 Philips screwdriver.
 - a. Press the tab on the front of the drive carrier, and pull the drive straight out of the chassis.





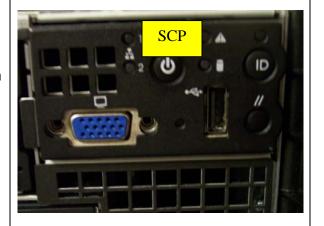
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E 2000 D2 /796 015	S_NY 796_N157_NY 79	6 01E0 0V 70	6 04E0 0V\

- b. Remove the four (4) screws securing the drive to the carrier (two on each side). (repeat for each drive installed)
 - c. Discard the Hard Drive(s), Carriers, and screws in the appropriate Recycling Bin.





- 24. Removal of the Standard Control Panel (SCP) (if present) requires a #2 Philips screwdriver.
 - a. For 3.5" HDD enclosure, press the latch at the rear of the Standard Control Panel and push it towards the front of the chassis.
 - For 2.5" HDD enclosure, disconnect the two cables from the midplane, press the latch at the rear of the SCP, and push it towards the front of the chassis.
 - c. Slide the panel out of the chassis.
 - d. For 2.5" HDD enclosure, disconnect all cables from the

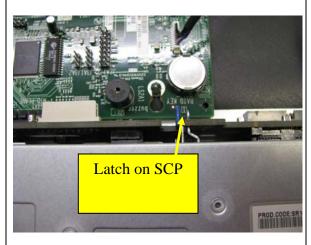


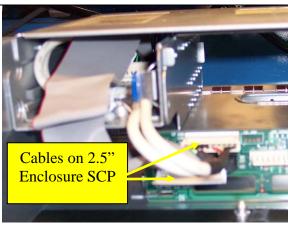
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E_2000 P2 /786_0156	S_NY 786_N157_NY 786	S_015Q_0Y 7Q	6_0150_0Y\

SCP.

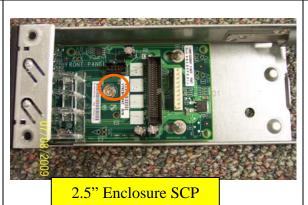
- e. Remove the screw securing the control board to the panel bracket.
- f. Press the panel bezel tabs on the underside of the bezel bracket, and pull the bezel off.
- g. Discard the Standard Control Panel, control board, bezel, panel bracket, and screw in the appropriate Recycling Bin.

24.





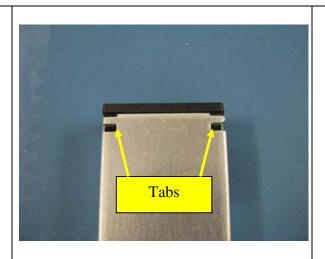
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3.5" Enclosure SCP

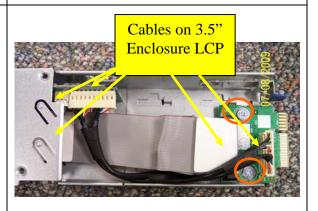
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Assemblies Covered:	6-0X. 786-0157-0X. 78		



- 25. Removal of the Local Control Panel (LCP) (if present) requires a #2 Philips screwdriver.
 - a. Disconnect the two cables attached to the backplane.
 - b. Press the latch towards the side of the chassis, and pull the panel out through the front (as shown in step 24).

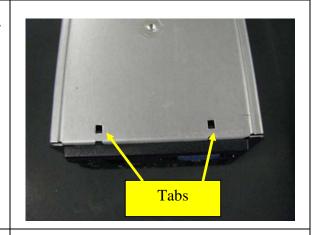


- 25.
- c. Remove the screw on the rear of the panel assembly.
- d. Disconnect and remove the cables from the controller board and LCD.
- e. Remove the screw from the controller board and pull out of the assembly.
- f. Remove the two screws from the LCD and pull out of the assembly

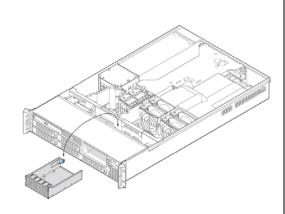


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g. Press in the two bezel clips on the bottom of the panel assembly and pull off the bezel. h. Discard the LCD, brackets, controller board, cables, and screws in the appropriate Recycling Bin.



- 26. Removal of the 3.5" Tape Drive Filler Panel does not require any tools.
 - a. Press the blue release lever and pushing it forward to release it and then sliding it out from the front of the system.
 - Discard the tape drive filler panel in the appropriate Recycling Bin.



- 27. Removal of the 2.5" HDD Backplane requires a #2 Philips screwdriver.
 - c. Take screwdriver and unscrew thumbscrew from backplane.
 - d. Shift backplane towards the Control Panel side of the enclosure.
 - e. Carefully remove the backplane straight out towards you.
 - f. Discard the backplane in the appropriate Recycling Bin.



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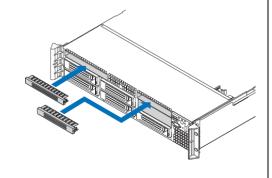
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28.	Removal of the 3.5" HDD Backplane does not require a tool. a. Firmly grasp the top of the backplane and remove the backplane from the server system by pulling straight up. b. Remove 6 th HDD Option (if present). c. Discard the backplane in the appropriate Recycling Bin.	
28.	6 th HDD Option	
29.	Removal of the IO Expansion Module (if present) does not require any tools. a. Pull the module straight up to disengage from the standoffs and motherboard connectors. b. Pull the standoffs straight up and out of the motherboard c. Discard the IO Expansion Module and standoffs in the appropriate Recycling Bin.	Standoff Hide Servet Board 10 Corrector 1 Filter Panels

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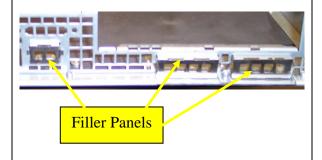
- 30. Removal of the motherboard requires a Phillips #2 screwdriver.
 - a. Unscrew all remaining screws on motherboard.
 - b. Lift motherboard straight out of server.
 - c. Discard the Motherboard and screws in the appropriate Recycling Bin.



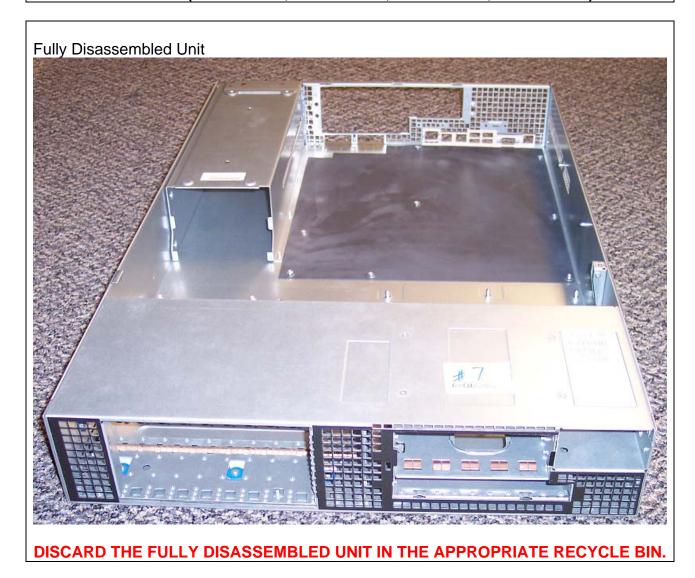
- 31. Removal of any remaining front filler panels present does not require any tools.
 - Carefully pry the panel out from both sides from the front of the system.
 - b. Discard all filler panel in the appropriate Recycling Bin.



- 32. Removal of any I/O Expansion Module Filler Panels does not require any tools.
 - Squeeze the sides of the I/O expansion module filler panel(s) to disengage it from the server system back panel and remove it.
 - b. Discard the filler panels in the appropriate Recycling Bin.



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Recycling/Material Code	Important Information			
Material /Components, which must be removed and treated separately				
Lithium Battery	Battery free of hazardous substances,			
	installed in socket on the motherboard			
Lithium Ion RAID Battery Backup	Battery is RoHS 5/6, installed beside the			
	active mid-plane			
RAID Activation Key	RAID Activation Key free of hazardous			
	substances, installed in socket on the mid-			
	plane			

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** LCD-Display	LCD control board background lighting contains Hg
Printed circuit boards	Motherboard, DIMMs, PCI card, PCI riser, Power Supply, Active Mid-Plane, Backplane, RAID DIMM, Power Distribution Board, IO Expansion Module, Remote Management Module, Bridge Board, & Front Panel Control Board
Disk Drives	Mounted on disk carrier
Material /Components, which can disturb	certain recycling processes
Copper	Fansink
Material /Components, through which be	nefits can normally be achieved
Cold Rolled Steel	Fixed cover, PCI bracket, & chassis
* ABS	Bezel, Control Panel Bezel, Cable Guide, Power Distribution Board Cover, Fan Assembly, & Air Baffle
Cables	Distributed in device & power cord
Fans	Fan Assembly
Special notes	
** LCD display background lights contain Ho	
* Flame retardant of plastics do not contain	PBB and PBDE.

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Unit Disassembly for WEEE				
Document Number / Disk File: 597-1001-01	By: Shane McKinney	Current Rev: 0A	Date: 7/09/2009	
Assemblies Covered: F-2900 R2 (786-0156-0X, 786-0157-0X, 786-0158-0X, 786-0159-0X)				

Annex A

Producer:	<company addressing="" name,="" on="" other="" producer="" the=""></company>
	< product category as in Annex IA of WEEE Directive, or type of equipment as in Annex 1B of WEEE Directive, or producer's Product Family, or single products identified by brand and model name >

Component or Material	Remarks / Location
Battery (internal *) containing Mercury (Hg)/ NiCad/Lithium/ Other	Lithium battery ↓
	located on the motherboard
Backlighting lamps of LCD/TFT or similar screens containing Mercury (Hg)	NONE
Mercury (Hg) in other applications**	NONE
Cadmium**	NONE
Gas discharge lamps	NONE
Plastic containing brominated flame retardants other than in Printed Circuit Assemblies ***	NONE
Liquid Crystal Displays with a surface greater than 100 cm2	NONE
Capacitors with PCB's	NONE
Capacitors with substances of concern**** + height > 25 mm, diameter > 25 mm or proportionately similar volume	NONE
Asbestos	NONE
Refractory ceramic fibres	NONE
Radio-active substances	NONE
Beryllium Oxide	NONE
Other forms of Beryllium	BE-CU in some connector contacts
Gasses - which fall under Regulation (EC) 2037/2000 and all hydrocarbons (HC).	NONE
Components with pressurised gas which need special attention (Pressure > 1,5 bar) *****	NONE
Liquids ***** if volume > 10 cl (or equivalence in weight, e.g. for PCB, oil)	NONE
Mechanical components that store mechanical energy (i.e. springs) or equivalent parts which need special attention ***** (diameter > 10 mm and height > 25 mm or proportionally similar volume and expanding)	NONE
PBDE (deca- & octa-BDE) and Perfluorocatane sulfantes (PFOS) in Directive 2006/122/EC	NONE

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597-1001-01	Shane	0A	7/09/2009	
	McKinney			
Assemblies Covered:				
E-2900 R2 (786-0156-0X, 786-0157-0X, 786-0158-0X, 786-0159-0X)				

- **=** arrow indicates the need for the location of the compartment/ substances within the product. When the location of a substance/ components is requested, it is at part level, e.g. main board, housing etc
- * Internal means that batteries can only be removed by opening the product by means of (a) tool(s).
- ** Substances are considered to be in the product if present above the levels specified in Commission Decision 2005/618/EC related to Directive 2002/95/(EC) (RoHS Directive) or if their use is permitted through exemptions in the Annex of Directive 2002/95(EC)
- *** To be coherent with industry current standards and practices on tracking of plastic parts, Directive 2002/96 (EC) Annex II requirement is understood to focus on plastic parts that weight more than 25 g.
- **** Substance of concern other than PCB, to be specified/ addressed further in the context of Directive 2002/96 (EC) Annex II national requirements and European developments
- ***** Needs of equivalent nature as those for maintenance, service manuals and installation for safety purposes.